

Version of Claims With Markings to Show Changes Made:

Claim 1 (amended). A power semiconductor module, comprising:

semiconductor components;

a plastic housing having an interior and connecting element openings formed therein;

a substrate disposed in said plastic housing defining a housing base of said plastic housing, said substrate containing a ceramic plate having a top side and a bottom side with a top metallization layer disposed on said top side and a bottom metallization layer disposed on said bottom side, said top metallization layer facing said interior of said plastic housing being patterned in order to form interconnects and equipped for and receiving said semiconductor components;

[connecting elements interconnecting said semiconductor components ; and]

terminal elements for providing external terminals, said terminal elements press-fitted into said connecting element openings in said plastic housing; and

wires bonded to said terminal elements and to said semiconductor components.